

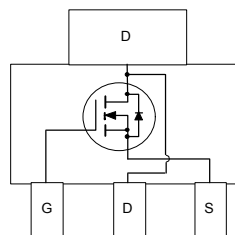
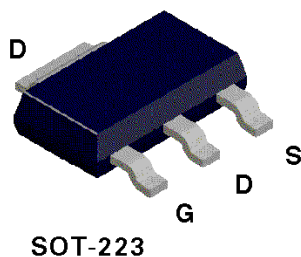
# **NDT451AN** **N-Channel Enhancement Mode Field Effect Transistor**

## **General Description**

Power SOT N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance and provide superior switching performance. These devices are particularly suited for low voltage applications such as DC motor control and DC/DC conversion where fast switching, low in-line power loss, and resistance to transients are needed.

## **Features**

- 7.2A, 30V.  $R_{DS(ON)} = 0.035\Omega @ V_{GS} = 10V$   
 $R_{DS(ON)} = 0.05\Omega @ V_{GS} = 4.5V$ .
- High density cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handling capability in a widely used surface mount package.



## **Absolute Maximum Ratings** $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	NDT451AN	Units
$V_{DSS}$	Drain-Source Voltage	30	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current - Continuous (Note 1a) - Pulsed	$\pm 7.2$	A
		$\pm 25$	
$P_D$	Maximum Power Dissipation (Note 1a) (Note 1b) (Note 1c)	3	W
		1.3	
		1.1	
$T_J, T_{STG}$	Operating and Storage Temperature Range	-65 to 150	$^\circ\text{C}$

## **THERMAL CHARACTERISTICS**

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	42	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	12	$^\circ\text{C/W}$

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	30			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
		$T_J = 55^\circ\text{C}$			10	$\mu\text{A}$
$I_{GSSF}$	Gate - Body Leakage, Forward	$V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$			100	nA
$I_{GSSR}$	Gate - Body Leakage, Reverse	$V_{GS} = -20\text{ V}, V_{DS} = 0\text{ V}$			-100	nA
ON CHARACTERISTICS (Note 2)						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	1	1.6	3	V
		$T_J = 125^\circ\text{C}$	0.7	1.2	2.2	
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 7.2\text{ A}$		0.03	0.035	$\Omega$
		$T_J = 125^\circ\text{C}$		0.042	0.063	
		$V_{GS} = 4.5\text{ V}, I_D = 6.0\text{ A}$		0.042	0.05	
		$T_J = 125^\circ\text{C}$		0.058	0.09	
$I_{D(on)}$	On-State Drain Current	$V_{GS} = 10\text{ V}, V_{DS} = 5\text{ V}$	25			A
		$V_{GS} = 4.5\text{ V}, V_{DS} = 5\text{ V}$	15			
$g_{FS}$	Forward Transconductance	$V_{DS} = 10\text{ V}, I_D = 7.2\text{ A}$		11		S
DYNAMIC CHARACTERISTICS						
$C_{iss}$	Input Capacitance	$V_{DS} = 15\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$		720		pF
$C_{oss}$	Output Capacitance			370		pF
$C_{rss}$	Reverse Transfer Capacitance			250		pF
SWITCHING CHARACTERISTICS (Note 2)						
$t_{D(on)}$	Turn - On Delay Time	$V_{DD} = 10\text{ V}, I_D = 1\text{ A},$ $V_{GEN} = 10\text{ V}, R_{GEN} = 6\text{ }\Omega$		12	20	ns
$t_r$	Turn - On Rise Time			13	30	ns
$t_{D(off)}$	Turn - Off Delay Time			29	50	ns
$t_f$	Turn - Off Fall Time			10	20	ns
$Q_g$	Total Gate Charge	$V_{DS} = 10\text{ V},$ $I_D = 7.2\text{ A}, V_{GS} = 10\text{ V}$		19	30	nC
$Q_{gs}$	Gate-Source Charge			2.3		nC
$Q_{gd}$	Gate-Drain Charge			5.5		nC

Electrical Characteristics (T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				2.3	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 7.2A (Note 2)		0.9	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>F</sub> = 1.25 A, dI <sub>F</sub> /dt = 100 A/μs			100	ns

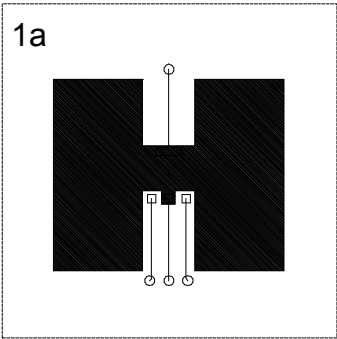
Notes:

1. R<sub>θJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>θJC</sub> is guaranteed by design while R<sub>θCA</sub> is determined by the user's board design.

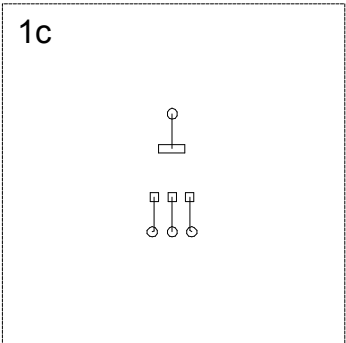
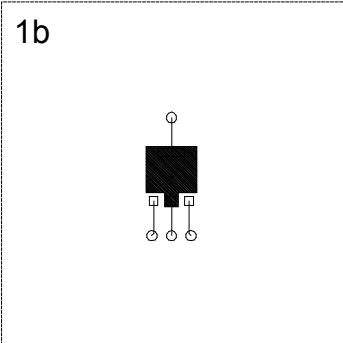
$$P_D(t) = \frac{T_J - T_A}{R_{\theta J}(t)} = \frac{T_J - T_A}{R_{\theta J} + R_{\theta CA}(t)} = I_D^2(t) \times R_{DS(on)} @ T_J$$

Typical R<sub>θJA</sub> using the board layouts shown below on 4.5"x5" FR-4 PCB in a still air environment:

- a. 42°C/W when mounted on a 1 in<sup>2</sup> pad of 2oz copper.
- b. 95°C/W when mounted on a 0.066 in<sup>2</sup> pad of 2oz copper.
- c. 110°C/W when mounted on a 0.0123 in<sup>2</sup> pad of 2oz copper.



Scale 1 : 1 on letter size paper



2. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%.

## Typical Electrical Characteristics

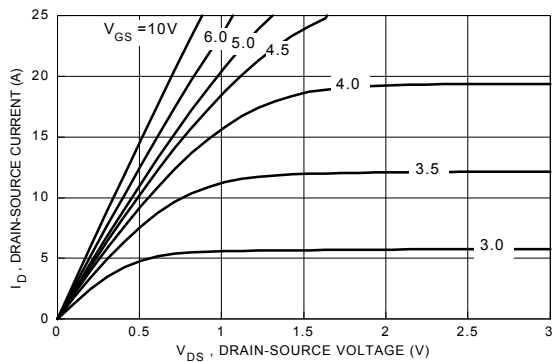


Figure 1. On-Region Characteristics.

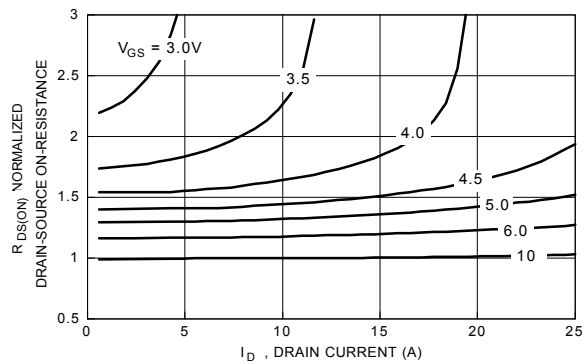


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current.

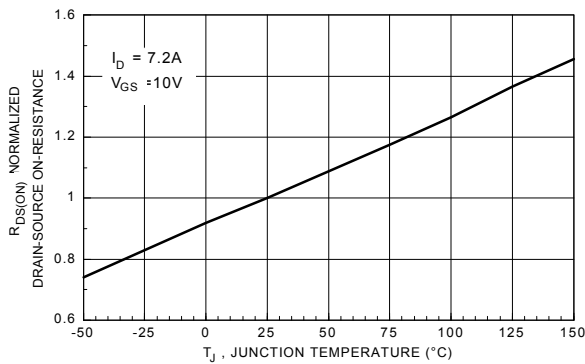


Figure 3. On-Resistance Variation with Temperature.

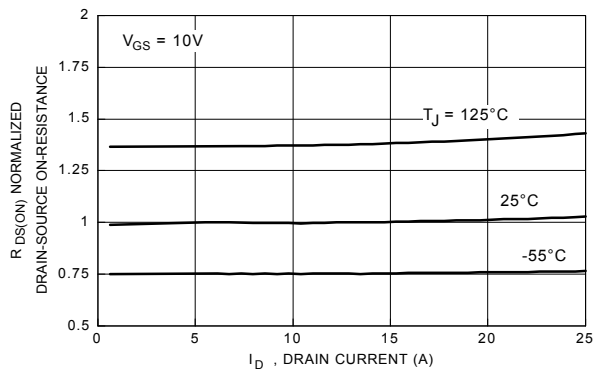


Figure 4. On-Resistance Variation with Drain Current and Temperature.

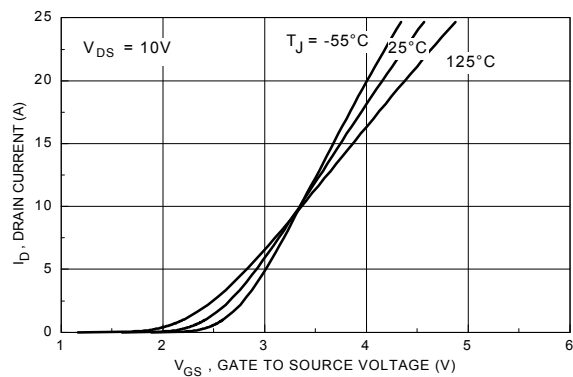


Figure 5. Transfer Characteristics.

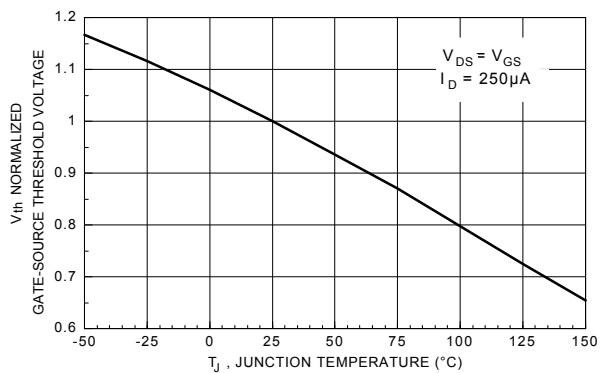
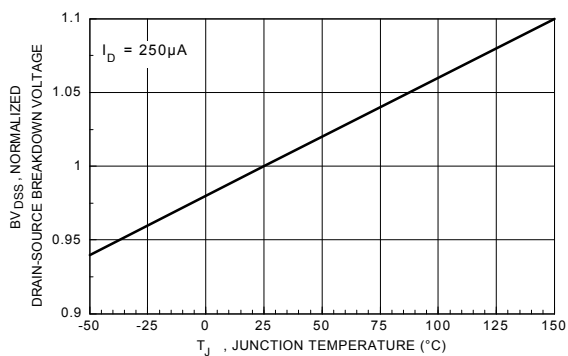
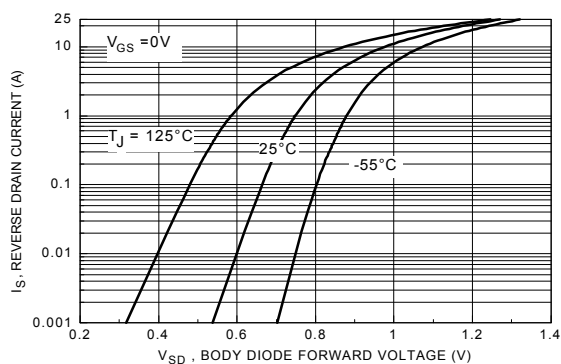


Figure 6. Gate Threshold Variation with Temperature.

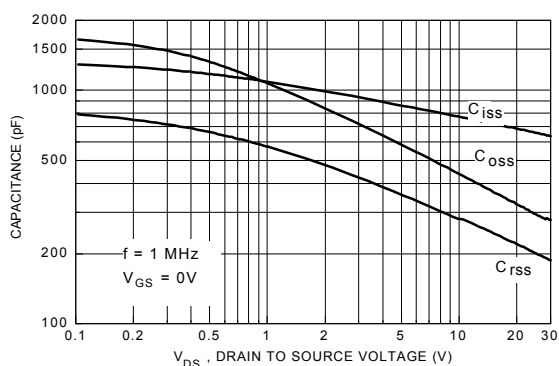
## Typical Electrical Characteristics



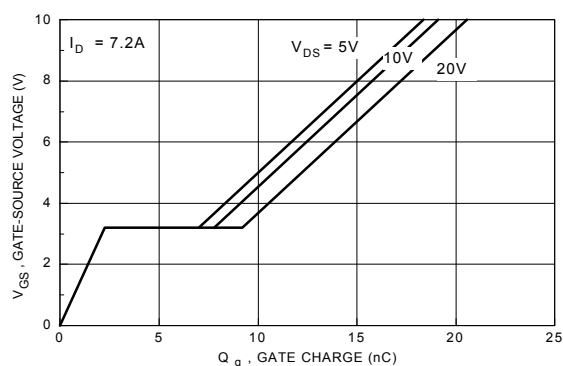
**Figure 7. Breakdown Voltage Variation with Temperature.**



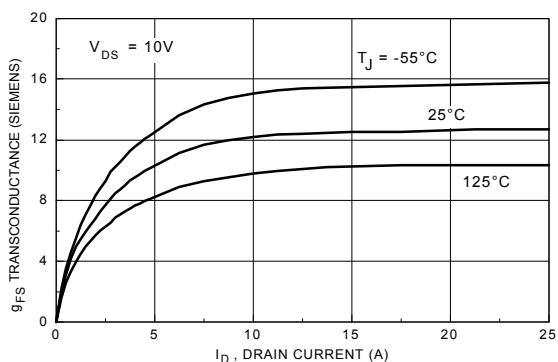
**Figure 8. Body Diode Forward Voltage Variation with Current and Temperature.**



**Figure 9. Capacitance Characteristics.**

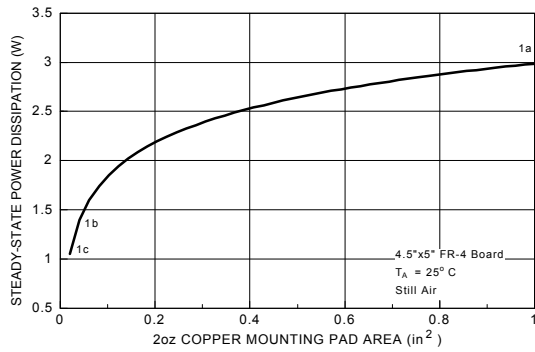


**Figure 10. Gate Charge Characteristics.**

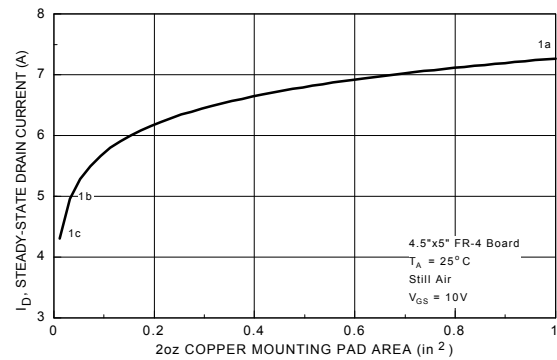


**Figure 11. Transconductance Variation with Drain Current and Temperature.**

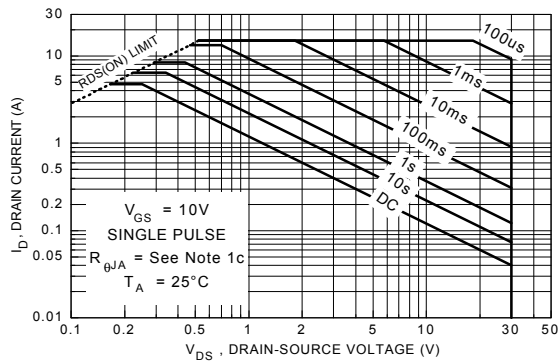
## Typical Thermal Characteristics



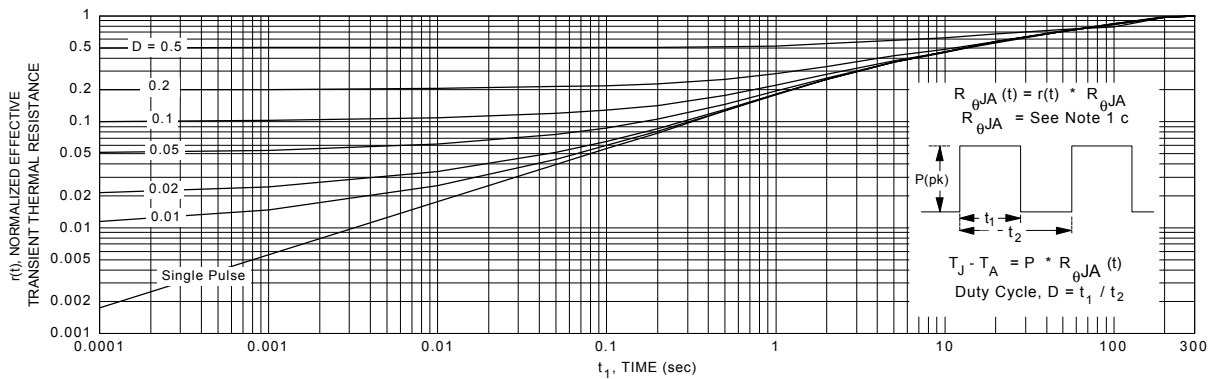
**Figure 12. SOT-223 Maximum Steady-State Power Dissipation versus Copper Mounting Pad Area.**



**Figure 13. Maximum Steady-State Drain Current versus Copper Mounting Pad Area.**



**Figure 14. Maximum Safe Operating Area.**



**Figure 15. Transient Thermal Response Curve.**


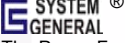
Note: Thermal characterization performed using the conditions described in note 1c. Transient thermal response will change depending on the circuit board design.

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